

### SKiiP 03NAC12T4V1

#### Features\*

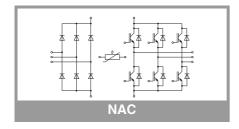
- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### **Remarks**

- Max. case temperature limited to T<sub>C</sub>=125°C
- Product reliability results valid for T<sub>j</sub>≤150°C (recommended T<sub>j,op</sub>=-40...+150°C)
- Temperature sensor: No basic insulation to main circuit, max. potential difference 850V to -DC

Absolute	Maximum Ratir	ngs		
Symbol	Conditions		Values	Unit
Inverter -	IGBT			,
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1200	V
Ic	T 150°C	T <sub>s</sub> = 25 °C	7.5	Α
	T <sub>j</sub> = 150 °C	T <sub>s</sub> = 70 °C	7.5	Α
I <sub>C</sub>	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 25 °C	7.5	Α
		T <sub>s</sub> = 70 °C	7.5	Α
I <sub>Cnom</sub>		,	8	Α
I <sub>CRM</sub>			24	Α
V <sub>GES</sub>			-20 20	V
t <sub>psc</sub>	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$	T <sub>j</sub> = 150 °C	10	μs
	V <sub>CES</sub> ≤ 1200 V			
Tj			-40 175	°C
Inverse -				
$V_{RRM}$	T <sub>j</sub> = 25 °C		1200	V
l <sub>F</sub>	_ T <sub>i</sub> = 150 °C	T <sub>s</sub> = 25 °C	9	Α
	1, 1,000	T <sub>s</sub> = 70 °C	9	Α
l <sub>F</sub>	T <sub>i</sub> = 175 °C	$T_s = 25  ^{\circ}C$	9	Α
	1,1 - 1,70 0	T <sub>s</sub> = 70 °C	9	Α
I <sub>FRM</sub>			24	Α
I <sub>FSM</sub>	$t_p = 10 \text{ ms, sin } 180^{\circ}, T_j = 150 ^{\circ}\text{C}$		36	Α
Tj			-40 175	°C
Rectifier -	- Diode			
$V_{RRM}$	T <sub>j</sub> = 25 °C		1600	V
I <sub>F</sub>	$T_s = 25  ^{\circ}C, T_j = 1$	50 °C	39	Α
I <sub>FSM</sub>	$t_p = 10 \text{ ms}$	T <sub>j</sub> = 25 °C	220	Α
	sin 180°	T <sub>j</sub> = 150 °C	200	Α
i <sup>2</sup> t	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	242	A <sup>2</sup> s
	sin 180°	T <sub>j</sub> = 150 °C	200	A <sup>2</sup> s
Tj		,	-40 150	°C
Module	•	<u> </u>		
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C,	20 A per spring	t.b.d.	Α
T <sub>stg</sub>	module without	· · · · · ·	-40 125	°C
V <sub>isol</sub>	AC sinus 50 Hz,	1 min	2500	V

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Inverter -	Inverter - IGBT							
V <sub>CE(sat)</sub>	I <sub>C</sub> = 8 A	T <sub>j</sub> = 25 °C		1.85	2.10	V		
V <sub>GE</sub> = 15 V chiplevel		T <sub>j</sub> = 150 °C		2.25	2.45	V		
$V_{CE0}$	chiplevel	T <sub>j</sub> = 25 °C		0.80	0.90	V		
		T <sub>j</sub> = 150 °C		0.70	0.80	V		
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25 °C		131	150	mΩ		
	chiplevel	T <sub>j</sub> = 150 °C		194	206	mΩ		
$V_{GE(th)}$	V <sub>GE</sub> = V <sub>CE</sub> V, I <sub>C</sub> = 1 mA		5	5.8	6.5	V		
I <sub>CES</sub>	$V_{GE} = 0 V$	T <sub>j</sub> = 25 °C			1	mA		
	V <sub>CE</sub> = 1200 V			-		mA		
C <sub>ies</sub>	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		0.49		nF		
Coes		f = 1 MHz		0.05		nF		
C <sub>res</sub>		f = 1 MHz		0.03		nF		





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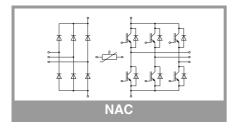
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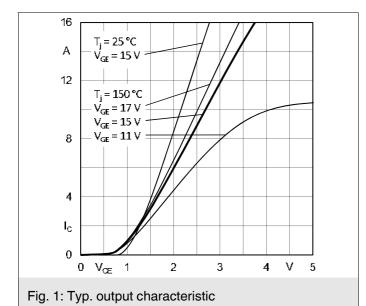
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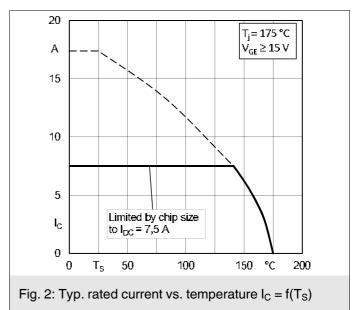
#### **Remarks**

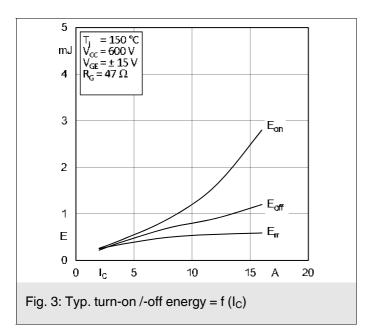
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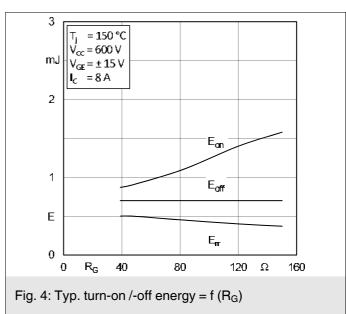
Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Inverter - IGBT								
$Q_{G}$	V <sub>GE</sub> = - 8 V+ 15	V	45			nC		
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			0		Ω		
t <sub>d(on)</sub>	V <sub>CC</sub> = 600 V	T <sub>j</sub> = 150 °C		32		ns		
t <sub>r</sub>	I <sub>C</sub> = 8 A	T <sub>j</sub> = 150 °C		34		ns		
E <sub>on</sub>	$R_{G \text{ on}} = 47 \Omega$ $R_{G \text{ off}} = 47 \Omega$	T <sub>j</sub> = 150 °C		0.9		mJ		
t <sub>d(off)</sub>	□G off — 47 32	T <sub>j</sub> = 150 °C	295			ns		
t <sub>f</sub>		T <sub>j</sub> = 150 °C		ns				
E <sub>off</sub>	$V_{GE} = +15/-15 \text{ V}$	T <sub>j</sub> = 150 °C		0.7		mJ		
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =0	.8 W/(K*m)		1.84		K/W		
Inverse -	Diode							
$V_F = V_{EC}$	I <sub>F</sub> = 8 A	T <sub>j</sub> = 25 °C		2.33	2.65	V		
	V <sub>GE</sub> = 0 V chiplevel	T <sub>j</sub> = 150 °C		2.35	2.68	V		
$V_{F0}$	chiplevel	T <sub>j</sub> = 25 °C		1.30	1.50	V		
	Criipievei	T <sub>j</sub> = 150 °C		0.90	1.10	V		
r <sub>F</sub>	chinlevel	T <sub>j</sub> = 25 °C		129	144	$m\Omega$		
	chiplevel	T <sub>j</sub> = 150 °C		181	198	$m\Omega$		
I <sub>RRM</sub>	$I_F = 8 A$	T <sub>j</sub> = 150 °C		7.7		Α		
Q <sub>rr</sub>	V <sub>GE</sub> = -15 V V <sub>CC</sub> = 600 V	T <sub>j</sub> = 150 °C		1.23		μC		
Err	$di/dt_{off} = 335 \text{ A/}\mu\text{s}$	T <sub>j</sub> = 150 °C		0.5		mJ		
R <sub>th(j-s)</sub>	per Diode, λ <sub>paste</sub> =0.8 W/(K*m)			2.53		K/W		
Rectifier -	- Diode							
$V_F = V_{EC}$	I <sub>F</sub> = 8 A	T <sub>j</sub> = 25 °C		1.00	1.21	V		
	- Diode	T <sub>j</sub> = 125 °C		0.90	1.10	V		
$V_{F0}$	chiplevel	T <sub>j</sub> = 25 °C		0.88	0.98	V		
	Criipievei	T <sub>j</sub> = 125 °C		0.73	0.83	V		
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		15	29	mΩ		
	omplever	T <sub>j</sub> = 125 °C		21	34	mΩ		
R <sub>th(j-s)</sub>	per Diode, $\lambda_{paste}=0$	0.8 W/(K*m)		1.5		K/W		
Module								
Ms	to heat sink		2		2.5	Nm		
w				20		g		
Temperat	ture Sensor							
R <sub>100</sub>	T <sub>r</sub> = 100 °C, tolerance = 3 %			1670 ± 3%		Ω		
R <sub>(T)</sub>	$R_{(T)}=1000\Omega[1+A(T)]$ , $A = 7.635*10^{-3}$ °C $B = 1.731*10^{-5}$ °C							

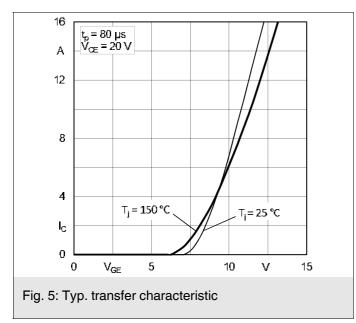


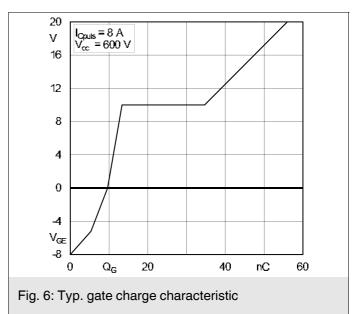


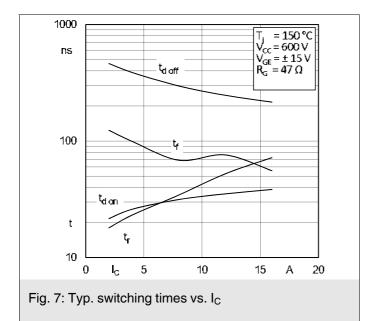


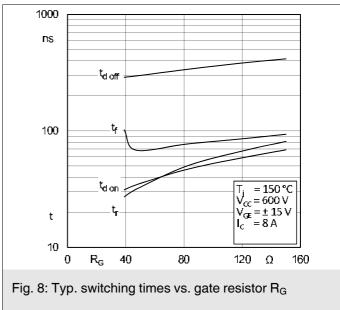


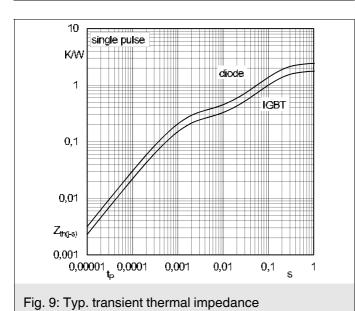


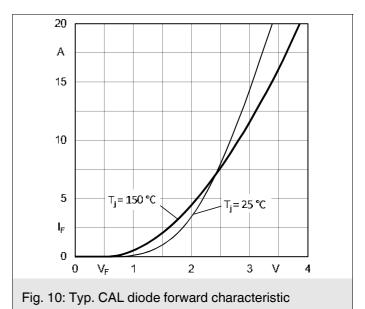


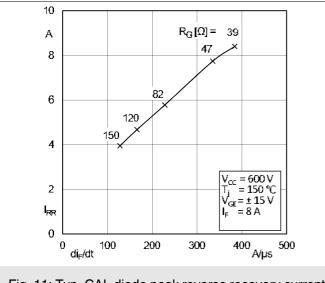












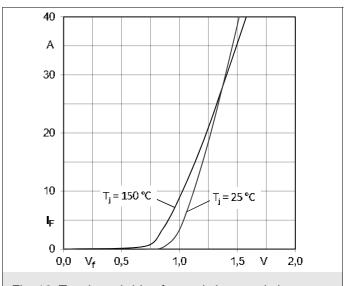
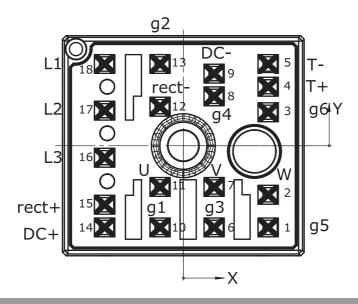


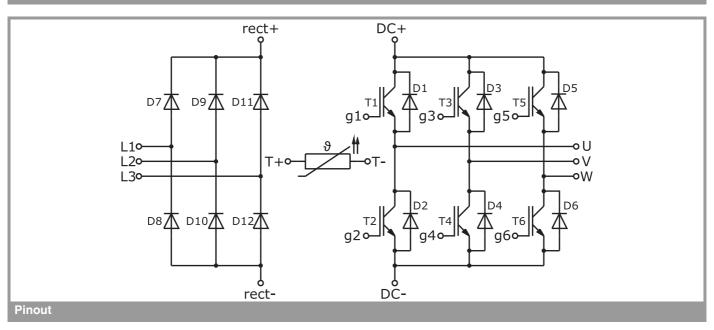
Fig. 11: Typ. CAL diode peak reverse recovery current

	Pin out						
Pin	Χ	Υ	Function	Pin	X	Υ	Function
1	11,93	-11,50	g5	10	-3,28	-11,50	g1
2	11,93	-6,90	W	11	-3,28	-5,80	U
3	11,93	4,71	g6	12	-3,28	5,50	rect-
4	11,93	8,3	T+	13	-3,28	11,50	g2
5	11,93	11,50	T-	14	-11,08	-11,50	DC+
6	4,33	-11,50	g3	15	-11,08	-8,30	rect+
7	4,33	-5,80	V	16	-11,08	-1,68	L3
8	4,33	6,95	g4	17	-11,08	4,93	L2
9	4,33	10,15	DC-	18	-11,08	11,50	L1

all values in mm



### **Pinout and Dimensions**



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### \*IMPORTANT INFORMATION AND WARNINGS

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